



Docket No.: M4065.0018/P018-A  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Rodney C. Langley et al.

Allowed: June 8, 2004

Application No.: 09/507,465

Confirmation No.: 2423

Filed: February 22, 2000

Art Unit: 1765

For: METHOD AND APPARATUS FOR  
PLASMA ETCHING A WAFER

Examiner: M. A. Anderson

**COMMUNICATION REGARDING DRAWINGS**

U.S. Patent and Trademark Office  
220 20th Street S.  
Customer Window, Mail Stop PGPUB Drawings  
Crystal Plaza Two, Lobby, Room 1B03  
Arlington, VA 22202

Dear Sir:

Although the Examiner stated in the Notice of Allowance dated June 8, 2004 that the drawings for the above-identified application submitted February 22, 2000 were accepted, in reviewing the case after allowance, Applicants' representative noticed that the drawings were originally objected to after review by a draftsperson on February 15, 2001. The draftsperson objected to the margins of FIGS. 4A and 4B.

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In order to ensure that the drawings in this case comply with all PTO Rules,  
Applicants hereby resubmit FIGS. 4A and 4B with proper margins.

Dated: July 12, 2004

Respectfully submitted,

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